

1

2

3

4

5

6

AGILENT RESTRICTED

THIS DOCUMENT AND ANY ASSOCIATED DATA CONTAIN RESTRICTED INFORMATION THAT IS AGILENT TECHNOLOGIES PROPERTY. ONLY DISCLOSE OR DUPLICATE FOR OTHERS AS AUTHORIZED BY AGILENT TECHNOLOGIES.

REFERENCE 3D MODEL EXISTS

THE 3D GEOMETRY MAY NOT MATCH THIS DRAWING. THIS 2D DRAWING IS THE GEOMETRY AND ANNOTATION MASTER.

OVERALL STACKUP

Layer 1 (RIGID) Topside SMT Pads

Layer 2 (RIGID) GND Plane

Layer 3 (RIGID) GND Plane

Layer 4 (RIGID) Buried Resistors

Layer 5 (FLEX) GND Plane

Layer 6 (FLEX) 75 Ohm Microstrip & Pads

Layer 7 (RIGID) Signal

Layer 8 (RIGID) GND Plane

Layer 9 (RIGID) Bottomside SMT Pads

Trace widths measured at base of trace
All dimensions in inches (unless otherwise noted)
All values calculated using a frequency of 1.85GHz

9.

FINGERS PLATED WITH HARD GOLD

0.106

COVER LAYER

0.229

COVER LAYER

.229

FINGERS PLATED WITH HARD GOLD

9.

SEE DETAIL-2

SEE DETAIL-1

R0.008±0.002

0.168

0.547

0.835

.180

0.047±0.002

0.028±0.002

R0.008±0.002

0.023±0.002

R0.010±0.002

0.334

1.004

DETAIL-2

SCALE 10X

0.008±0.001

COVER LAYER

FLEX

DETAIL-1


SCALE 5X

TYP. (4) PLCS

NOTES:

1. REVISION ON FACE OF BOARD: 001

2. PCB DESIGNED PER IPC-A-600.

3.  IS A CRITICAL DIMENSION.

4. VENDOR MAY ADD COPPER BALANCE PADS TO OUTER LAYERS. COPPER BALANCE PADS MUST AVOID ANY PRE-EXISTING COPPER FEATURE (COMPONENT PADS, TRACES, CONDUCTIVE AREAS..)BY 0.100".

5. VENDOR MAY ALTER PHOTO DATA (GERBER) TO COMPENSATE FOR ETCHING PROCESS.

6. CONTROLLED IMPEDANCE REQUIREMENTS AND TOLERANCES FOR EACH LAYER ARE SHOWN IN THE MATERIAL STACK-UP TABLE.

7. ALL IMPEDANCE COUPONS MUST BE SERIALIZED TO INDICATE WHICH BOARD THEY CORRESPOND TO. IMPEDANCE COUPONS SUPPLIED WITH BOARDS.

8. BURIED RESISTOR VALUE: 150 OHM ±20% TICER, 50 OHMS/SQUARE.

9. SOFT GOLD PLATING (3 - 10 microinches) FOR SOLDER AREAS. GRADE C CLASS 1 HARD GOLD PLATING (50 microinches minimum) FOR SIGNAL FINGERS.

10.SOLDERMASK OVER GOLD (SMOG) & SOLDERMASK OVER BARE COPPER (SMOBC) ARE ACCEPTABLE.

FILE NAME

W3631-26401.ami

REVISION

A.1

STORE DATE

2008-08-27

DOCUMENT NUMBER

W3631-26401

SYM

A.0

PRELIMINARY

REVISIONS

Note 1 was: rev on board 002

REVISED BY

F. LERI

DATE

2008-08-27

REVISED BY

F. LERI

DATE

2008-09-05

Lay #

Thick (in)

Picture


Type Dk Df

Description

Drill Picture

Sub Assem Picture

0.0005/0.0005

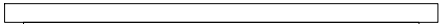


3

Soldermask

1

0.0022




F

1/2oz w/plating

1

0.0050




4.10 0.013

N7000-2 HT core

2

0.0006




P

1/2oz

2

0.0046

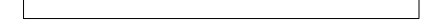


4.25 0.018

37N fill

3

0.0016




P

1/2oz w/plating

3

0.0100




4.08 0.013

N7000-2 HT core

4

0.0006




S

1/2oz

4

0.0047




4.25 0.018

37N fill

5

0.0013




P

1/2oz w/plating

5

0.0050




3.30 0.002

PYRALUX_AP core

0 1

6

0.0013




S

1/2oz w/plating

6


0.0050



4.25 0.018


37N fill

0.0000



None

0.0100




4.08 0.013

N7000-2 HT core

7

0.0016




S

1/2oz w/plating

7

0.0043




4.25 0.018

37N fill

8

0.0006




P

1/2oz

8

0.0100




4.08 0.013

N7000-2 HT core

9

0.0022




F

1/2oz w/plating

9

0.0005/0.0005



3

Soldermask

0.0707

Total thickness (in) over metal (no soldermask)

0.0675

After lamination thickness (in)

0.0674

Over laminate thickness (in) (with soldermask)

0.0720

Agilent requirement (in)

±0.0072

Agilent tolerance (in)

53.5

Calculated Board Resin Percentage by Weight

SPECIFIED BOARD THICKNESS: 0.072 ±10%

SOLDER RESIST TYPE IS LIQUID PHOTO IMAGE (LPI) - COLOR: RED

SAFETY REQUIREMENT: MATERIAL TO BE UL94V-0 OR EQUIVALENT

TOLERANCES UNLESS OTHERWISE SPECIFIED

±0.015

DO NOT SCALE THIS INCH DRAWING

GD&T SYMBOLOLOGY PER ASME Y14.5M-1994

F. LERI

DRAWN BY

F. LERI

ENGINEER/CHECKER

UNLESS OTHERWISE SPECIFIED

DIMENSIONS ARE IN INCHES

THIRD ANGLE PROJECTION

ADHERENCE TO DWG A-5951-1561-1 (COMPANY STD. SECTION 608) AND A-5951-1745-1 (GSE) IS REQUIRED

2008-08-27

DATE (YYYY-MM-DD)

2008-08-27

DATE

DDR3 X16


BGA PROBE – DATA ADDRESS, CONTROL

TITLE

1 OF 1 SHEET

2X SCALE

C SIZE



PART NUMBER

W3631-26401

W3631-26401

DOCUMENT NUMBER